

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	10/689976	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 18:22
L4	264	(257/e23.031).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/29 18:27
L7	219	257/e23.021	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 18:29
L8	19	257/e23.048	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 18:31
S1	4390	(257/777,686).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/28 19:22
S2	4037	(257/723,783).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/28 19:22
S3	5480	(257/786,778).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/28 19:22
S4	73500	(semiconductor chip die wafer) with stack\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 19:40

S5	84375	(ic integrated adj circuit substrate) with stack\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 19:41
S6	20231	S4 and S5 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 19:41
S7	27532	(semiconductor chip die wafer) with offset	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 19:42
S8	26047	(ic integrated adj circuit substrate) with offset	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 19:42
S9	3682	(S4 and S7) or (S5 and S8)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 19:43
S10	1650	S9 and "257"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 19:43
S11	9299	S6 and (@ad<"20021010")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 19:56
S12	748	S10 and (@ad<"20021010")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/28 19:56
S13	89	("4949163" "5019943" "5212406" "5373189" "5473196" "5600183" "5614766" "5656856").PN. OR ("5998864").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/28 20:51

S14	33	("20010015485" "5012323" "5128831" "5147815" "5291061" "5323060" "5399898" "5422435" "5434745" "5478781" "5483024" "5530287" "5585668" "5585675" "5635010" "5689135" "5723906" "5807762" "5899705" "5952725" "5963794" "5973403" "5998864" "6051878" "6051886" "6359340" "6376904" "6376914" "6461897" "6580035" "6621155" "6784019" "6900528").PN. OR ("7262506").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/28 20:52
S15	50	("4500905" "4706166" "4764846" "4879588" "5012323" "5247423" "5334962" "5481134" "5495398" "5600541" "5612657" "5675180" "5696031" "5698895" "5703436" "5777345" "5804004" "5864177" "5903736" "5998864" "6005778" "6072700" "6093969" "6133629" "6180881" "6181002" "6215182" "6229217" "6258623" "6376904").PN. OR ("6621155").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/28 20:53
S16	40	("5422435" "6005778").PN. OR ("6215182").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/28 20:54
S17	15	("20020158325" "4903114" "5091825" "5328079" "5422435" "5777345" "5877478" "6084294" "6148505" "6169331" "6215182" "6229217" "6376904" "6403895" "6476506").PN. OR ("7115977").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/28 20:55

S18	50	("4500905" "4706166" "4764846" "4879588" "5012323" "5247423" "5334962" "5481134" "5495398" "5600541" "5612657" "5675180" "5696031" "5698895" "5703436" "5777345" "5804004" "5864177" "5903736" "5998864" "6005778" "6072700" "6093969" "6133629" "6180881" "6181002" "6215182" "6229217" "6258623" "6376904").PN. OR ("6621155").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/28 20:56
S19	23	("5239447" "5323060" "5780925" "5874781" "5886412" "5963794" "5998864" "6181002" "6215192").PN. OR ("6461897").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/28 20:57
S20	18	("5276834" "5776797" "5777345" "5900008" "6168973" "6208521" "6225688" "6236109" "6239366" "6281578" "6359340" "6376904" "6461897" "6737750" "6781226" "6787901" "6787916" "6853064").PN. OR ("7030488").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/28 21:06
S21	8	"6768208"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 09:19
S22	14	("20030006494" "5340771" "5519176" "5783870" "5994166" "6188127" "6274929" "6335669" "6472741" "6489669" "6493229" "6608379" "6713375" "6768208").PN. OR ("7217993").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/29 09:19

S23	27	("20020074637" "20020121687" "20040178488" "20040178495" "20050006787" "5861666" "5872025" "5883426" "5963430" "6054337" "6147401" "6214640" "6222740" "6225688" "6232152" "6313528" "6376769" "6504241" "6740981" "6768208" "6770980" "6777798" "6869665" "6992395" "6998704" "7002080" "7053478").PN. OR ("7173325").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/29 09:21
S24	19	("2002/0074637").URPN.	USPAT	OR	ON	2008/03/29 09:21
S25	20	("4598307" "5475262" "5498906" "5608262" "5789303" "5814871" "5818748" "5854534" "5898223" "5926061" "5939782" "5963110" "5977640" "6521984" "6590281").PN. OR ("6768208").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/29 09:23
S26	18	("3400210" "5130894" "5434745" "5585675" "5612570" "5946553" "5995379" "6239496" "6271587" "6376904" "6392292" "6469375" "6611052" "6621155" "6740981" "6768208" "6873035").PN. OR ("7046522").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/29 09:24
S27	15	("5261115" "5373189" "5903049" "6141245" "6147398").PN. OR ("6392292").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/29 09:24
S28	67	("4956694" "5019943" "5128831" "5311401" "5313096").PN. OR ("5373189").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/29 09:25
S29	73	("5334857" "5376825" "5468997" "5677569" "5726493" "5798564" "6013948" "6020629" "6028365" "6037665" "6051886" "6051887" "6087717").PN. OR ("6239496").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/29 09:26
S30	8	("5847985" "5977783").PN. OR ("6521984").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/29 09:27

S31	363	(ic integrated adj circuit substrate) with offset with stack\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 09:29
S32	73500	(semiconductor chip die wafer) with stack\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 09:32
S33	84375	(ic integrated adj circuit substrate) with stack\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 09:32
S34	27532	(semiconductor chip die wafer) with offset	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 09:32
S35	26047	(ic integrated adj circuit substrate) with offset	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 09:32
S36	3682	(S32 and S34) or (S33 and S35)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 09:32
S37	1744	S36 and (@ad<"20021010")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 09:32
S38	4891	(semiconductor chip die wafer) with stagger\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 09:34
S39	4472	(ic integrated adj circuit substrate) with stagger\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 09:34

S40	4357	(S38 or S39) and (@ad<"20021010")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 09:35
S41	1262	(S32 or S33) and (S38 or S39)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 09:37
S42	1982	(substrate with stack\$3) and (substrate with (offset stagger\$4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 09:49
S43	6	((("5977640") or ("6621155") or ("6731009")).PN.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/29 09:58
S44	21	("5291062" "5550403" "5646828" "5760478" "5963429" "5973392" "6343019").PN. OR ("6731009").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/03/29 09:59
S45	1	10/689976	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 10:32
S46	583	S41 and (@ad<"20021010")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 10:34
S48	1960	(electrical\$3 and mechanical \$3 and offset).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:23
S49	3342	((semiconductor chip ic integrated adj circuit) with offset).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:24

S50	0	S49 and (mechanical\$3 with bypass).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:25
S53	10019	((semiconductor chip ic integrated adj circuit) and offset).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:27
S54	1	S53 and (mechanical\$3 with bypass).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:27
S55	344	(mechanical\$3 with bypass).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:28
S56	60	((electrical\$3 and mechanical \$3) with bypass).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:29
S57	8	S56 and (semiconductor chip ic integrated adj circuit die wafer substrate).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:30
S58	860	(electrical\$3 and mechanical \$3 and bump).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:31
S59	759	S58 and (semiconductor chip ic integrated adj circuit die wafer substrate).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:31
S60	252	((electrical\$3 and mechanical \$3) with bump).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:32

S61	237	S60 and (semiconductor chip ic integrated adj circuit die wafer substrate).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:32
S62	9551	(bump with (semiconductor chip ic integrated adj circuit die wafer substrate)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:35
S63	220	S60 and S62	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:36
S64	229	((electrical\$3 with mechanical \$3) same bump).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:36
S65	197	S62 and S64	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:37
S66	15051	(substrate with interconnect \$4).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:40
S67	2174	((mirror symmetrical\$3) with interconnect\$4).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:41
S68	187	S66 and S67	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 11:41
S69	3629	(257/773,776).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/29 11:45

S70	3629	(257/773,776).CCLS.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/03/29 16:32
S71	344	(mechanical\$3 with bypass). clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 16:35
S72	20	S71 and (semiconductor chip ic integrated adj circuit die wafer substrate).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 16:35
S73	1755	((mirror symmetric\$3) with interconnect\$4).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 16:36
S74	27912	(interconnect\$3 with (semiconductor chip ic integrated adj circuit die wafer substrate)).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 16:38
S75	255	S73 and S74	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 16:39
S76	1118	(symmetrical\$3 with interconnect\$4).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 16:41
S77	114	S74 and S76	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 16:42
S78	9	(S75 or S77) and (backside back adj side).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 16:43

S79	6	(S75 or S77) and (rear).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 16:43
S80	41	(S75 or S77) and (back).clm.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/03/29 16:43

3/29/08 7:31:19 PM

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